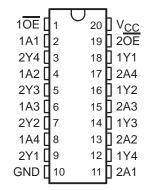
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- High-Impedance State During Power Up and Power Down
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Ceramic (J) DIPs

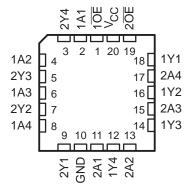
description

These octal buffers/drivers are designed specifically for low-voltage (3.3-V) V_{CC} operation with the capability to provide a TTL interface to a 5-V system environment.

SN54LVTZ244 . . . J PACKAGE SN74LVTZ244 . . . DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LVTZ244 . . . FK PACKAGE (TOP VIEW)



These devices are organized as two 4-bit line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74LVTZ244 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LVTZ244 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVTZ244 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE (each buffer)

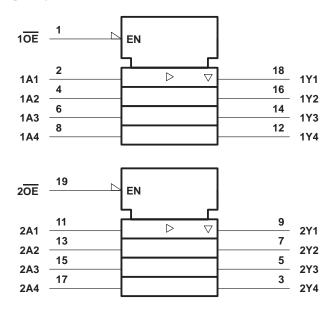
INP	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	X	Z



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

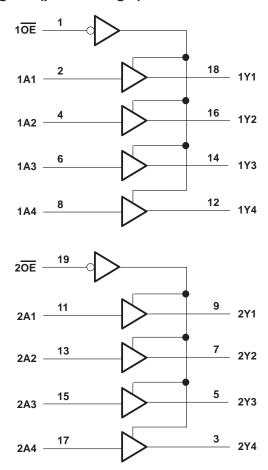


logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	$-0.5\;\mbox{V}$ to 7 \mbox{V}
Voltage range applied to any output in the high state or power-off state, V _O (see Note 1)	$-0.5\;\mbox{V}$ to 7 \mbox{V}
Current into any output in the low state, IO: SN54LVTZ244	96 mA
SN74LVTZ244	128 mA
Current into any output in the high state, IO (see Note 2): SN54LVTZ244	48 mA
SN74LVTZ244	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	50 mA
Output clamp current, I _{OK} (V _O < 0)	50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): DB package	0.6 W
DW package	1.6 W
PW package	0.7 W
Operating free-air temperature range, T _A : SN54LVTZ244 –5	55°C to 125°C
SN74LVTZ244 –	-40°C to 85°C
Storage temperature range, T _{stg} –6	35°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

			SN54LV	TZ244	SN74LVTZ244		
			MIN	MAX	MIN	MAX	UNIT
Vсс	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage	2	7	2		V	
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		5.5		5.5	V	
ЮН	High-level output current	<i>^</i>	-24		-32	mA	
lOL	Low-level output current	25	48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled	000	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

SN54LVTZ244, SN74LVTZ244 3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS				54LVTZ2	44	SN74LVTZ244			UNIT		
PARAMETER	'	MIN	TYP [†]	MAX	MIN	TYP†	MAX	UNII				
VIK	$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V			
	$V_{CC} = MIN \text{ to MAX}^{\ddagger}, I_{OH} = -100 \mu\text{A}$).2		VCC-C).2				
V	$V_{CC} = 2.7 \text{ V},$	2.4			2.4			V				
VOH	V _{CC} = 3 V	$I_{OH} = -24 \text{ mA}$		2						v		
	∧CC = 2 ∧	$I_{OH} = -32 \text{ mA}$				2						
	V _{CC} = 2.7 V	I _{OL} = 100 μA				0.2			0.2			
	VCC = 2.7 V	I _{OL} = 24 mA				0.5			0.5			
V		I _{OL} = 16 mA				0.4			0.4	V		
V_{OL}	V 2.V	I _{OL} = 32 mA			0.5			0.5	0.5			
	V _{CC} = 3 V	I _{OL} = 48 mA			0.55				1			
		I _{OL} = 64 mA						0.55				
	$V_{CC} = 0$ or MAX^{\ddagger} ,	V _I = 5.5 V		T		<u>)</u> 10			10			
1.	V _{CC} = 0 to 3.6 V	$V_I = V_{CC}$ or GND	Control inputs		1	±1			±1			
†į		VI = VCC	Data in suta		24	1			1	μΑ		
		V _I = 0	Data inputs		-5			-5				
l _{off}	V _{CC} = 0 V,	V_{I} or $V_{O} = 0$ to 4.5	J		5				±100	μΑ		
IOZPU§	$V_{CC} = 0 \text{ V to } 1.5 \text{ V},$	$V_0 = 0.5 \text{ V to 3 V},$	OE = X	Ó	?				±50	μΑ		
I _{OZPD} §	$V_{CC} = 1.5 \text{ V to } 0,$	$V_0 = 0.5 \text{ V to 3 V},$	OE = X	Q					±50	μΑ		
l	V 2.V	V _I = 0.8 V	A inmute	75			75			^		
l(hold)	VCC = 3 V	V _I = 2 V	A inputs	-75			-75			μΑ		
lozh	V _{CC} = 3.6 V,	V _O = 3 V		T		5			5	μΑ		
lozL	V _{CC} = 3.6 V,	V _O = 0.5 V				-5			-5	μΑ		
	V _{CC} = 3.6 V, I _O = 0,		Outputs high		0.12	0.5		0.12	0.225			
		$I_{O} = 0$,	Outputs low		8.6	15		8.6	15	mA		
	$V_I = V_{CC}$ or GND		Outputs disabled		0.12	0.5		0.12	0.225	IIIA		
ΔICC¶	V_{CC} = 3 V to 3.6 V, One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND					0.3			0.2	mA		
Ci	V _I = 3 V or 0				4			4		pF		
Co	V _O = 3 V or 0				8			8		pF		

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[§] This parameter is specified by characterization.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

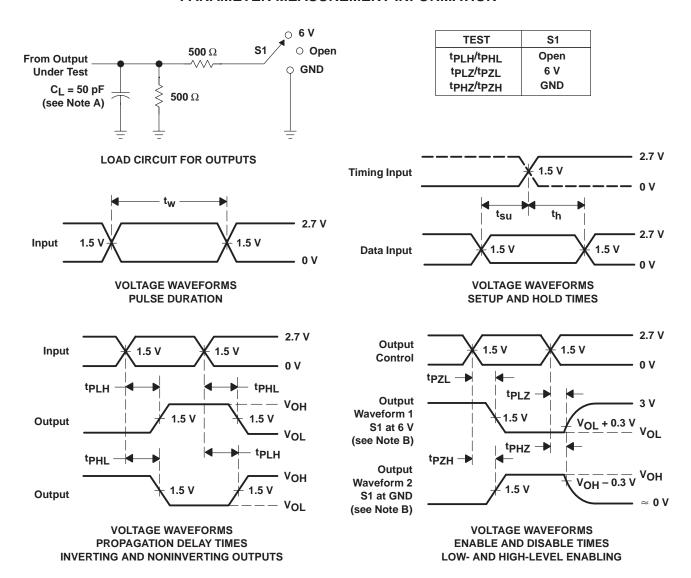
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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)	SN54LVTZ244				SN74LVTZ244						
PARAMETER	FROM (INPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX		
^t PLH	А	Y	1	4.7	3/1/	5.2	1	2.5	4.1		5	ns	
^t PHL			1	4.4	34	5.4	1	2.5	4.1		5.2	115	
^t PZH	ŌĒ	ŌĒ	V	1	5.4	14.	6.5	1	2.7	5.2		6.3	ns
t _{PZL}			r	1.1	5.4		7.6	1.1	3.1	5.2		6.7	115
^t PHZ	ŌĒ	OF V	1.9	6.2		6.9	1.9	3.9	5.6		6.3	20	
t _{PLZ}		OL 1		1.8	5.5		6	1.8	3.2	5.1		5.6	ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{r} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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